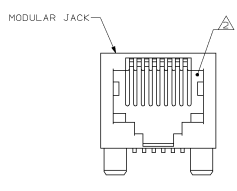
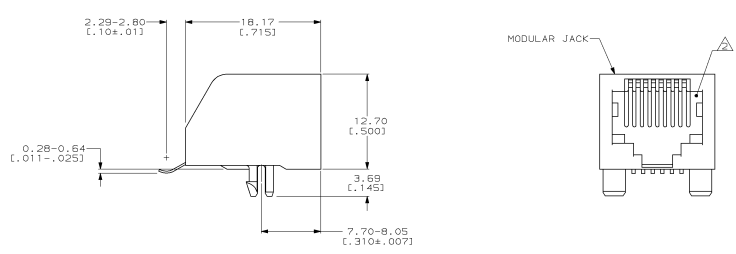
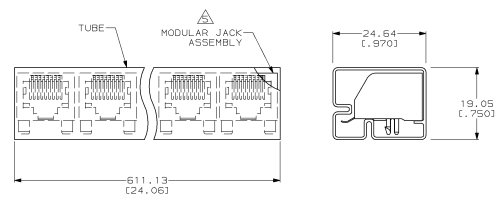
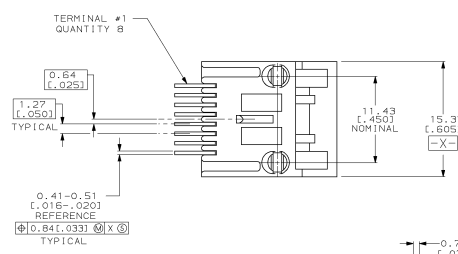


DRAWING MADE IN THIS ANGLE PROJECTION  
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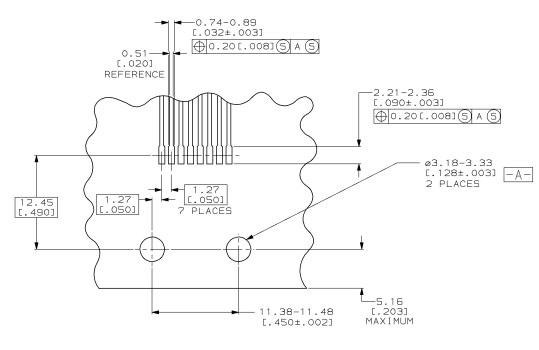
REV	DATE	DESCRIPTION	DATE	APP
AA	22	P	REV. EC 0502-0711-97	2300199



- △ MATERIAL: HOUSING - HTN MOLDING COMPOUND, 94 V0, BLACK.  
TERMINAL - 0.36 (.014) THICK PHOS-BRONZE PLATE WITH 1.27µm (.00050) MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm (.00150) MINIMUM THICK TIN-LEAD IN SOLDER AREA OVER 1.27µm (.00050) MINIMUM THICK NICKEL UNDERPLATE.
- △ CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 6B, SUBPART F.
- 3. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.
- 4. SNAP-IN RETENTION FEATURE ACCOMMODATES 1.45-1.70 (.062±.005) THICK PRINTED CIRCUIT BOARD.
- △ ASSEMBLIES ARE PACKAGED 36 IN A TUBE.
- △ ASSEMBLIES ARE BULK PACKAGED.



DETAIL A  
SCALE 2:1



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT

DO NOT SCALE PRINT. UNLESS SPECIFIED DIMENSIONS IN mm (INCHES) TOLERANCES ON: 2 PLG DEC ± .005 INCHES ± .005	DR 9-28-95 D. STRAUSSER CHK 10-17-95 R. JONES APPD 10-23-95 J. TONEY PRODUCT SPEC 10B-1163	OR 114-6040 H. HIGASHI MATERIAL 10B-1163 FINISH	AMP Incorporated Harrisburg, PA 17105-3608 NAME MODULAR JACK ASSEMBLY, 8 POSITION, LOW PROFILE, RIGHT ANGLE, SURFACE MOUNT SIZE 00779 CAGE CODE 555764 DRAWING NO. 555764-3 555764-1 PART NO.
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THIS DRAWING IS A CONTROL DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING PART NUMBER IDENTIFICATION SHOULD BE CONTACTED FOR THE LATEST REVISION.

CUSTOMER DRAWING